

**REMARKS**

This is in response to the Office Action dated February 23, 2006. Claims 1 and 3-13 are pending.

**Claim 1**

Claim 1 stands rejected under 35 U.S.C. Section 103(a) as being allegedly unpatentable over Hieber in view of Nishizawa. This Section 103(a) rejection is respectfully traversed for at least the following reasons.

Claim 1 as amended requires “a temperature measuring section coupled to the proximal end of the thermocouple and provided in the vicinity of the hollow shaft for sensing a temperature of the wafer through the thermocouple and converting the sensed temperature into a first signal; . . . . a system for circulating cooling water in the hollow shaft to cool the temperature measuring section coupled to the proximal end of the thermocouple.” The cited art fails to disclose or suggest these features of claim 1. Each of Hieber and Nishizawa fails to disclose or suggest these features recited in claim 1.

**Claim 11**

Claim 11 as amended requires “a cooling section for cooling at least one of the temperature measuring section and the signal generating section, wherein the cooling section comprises a system for circulating cooling fluid in the hollow shaft to cool the temperature measuring section coupled to the proximal end of the temperature sensing device.” The cited art fails to disclose or suggest these features of claim 11. Imahashi, cited by the Office Action for a cooling system, merely discloses a cooling system for cooling a wafer. Imahashi mentions nothing about cooling a temperature measuring section and/or a signal generating section, and mentions nothing about circulating cooling fluid in a hollow shaft of a rotary table section to cool

a temperature measuring section coupled to a proximal end of a temperature sensing device.

Thus, the cited art fails to disclose or suggest the invention of claim 11 in these respects.

Claim 13

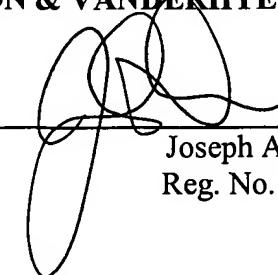
Claim 13 requires that "a distal end of the thermocouple projects outwardly from a surface of the rotary table so as to be brought into close relation to or in contact with a bottom surface of the wafer." E.g., see page 9, lines 1-4, and Fig. 2, of the instant application. In addition to failing to meet claim 1, Hieber and Nishizawa also fail to disclose or suggest this feature of claim 13. In the previous Office Action, the Office Action appears to be contending that the temperature sensing element of Hieber includes not only elements 14 and 15, but also contacts 2-6. This allegation lacks merit. Contacts 2-6 in Hieber are for measuring electrical resistance, not temperature. Thus, contacts 2-6 in Hieber are *not* part of the thermometers 14 and 15. Because contacts 2-6 in Hieber are not part of the temperature sensing elements 14, 15, the aforesaid italicized feature of claim 13 cannot be met by Hieber. Moreover, citation to Nishizawa cannot cure the aforesaid flaws in Hieber. Thus, even the alleged combination (which applicant believes would be incorrect in any event) fails to meet the invention of claim 13.

For at least the aforesaid reasons, it is respectfully requested that all rejections be withdrawn. All claims are in condition for allowance. If any minor matter remains to be resolved, the Examiner is invited to telephone the undersigned with regard to the same.

KINEI  
Appl. No. 10/730,358  
July 20, 2006

Respectfully submitted,

**NIXON & VANDERHYE P.C.**

By: 

Joseph A. Rhoa  
Reg. No. 37,515

JAR:caj  
901 North Glebe Road, 11th Floor  
Arlington, VA 22203-1808  
Telephone: (703) 816-4000  
Facsimile: (703) 816-4100